

PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A processing apparatus includes a wafer carrying-out unit, a wafer table that supports a wafer carried out, a frame carrying-out unit, a frame table that supports an annular frame carried out, a tape sticking unit that sticks a tape to the frame, a tape-attached frame conveying unit, a tape pressure bonding unit that executes pressure bonding of the tape of a tape-attached frame to a back surface of the wafer, a frame unit carrying-out unit, and a beveled part removing unit that cuts and removes, in a ring manner, a beveled part formed in an outer circumferential surplus region from the wafer of a frame unit.

[Fig. 1]